Fairchild Semiconductor Product Package Material Disclosure

Package Type	**BGA 4.3 x 5.5 (FLF BGA)**						
Weight of Package (grams)	**9.92E-02**						
Component	Material	Weight in grams	Substance in material	Wt% in component	Wt% in finished product	CAS #	Parts per Million
Frame	Copper Alloy	8.15E-02			82.12		821204
			Copper	96.08	78.90	7440-50-8	789013
			Iron	2.40	1.97	7439-89-6	19709
			Zinc	0.13	0.11	7440-66-6	1068
			Nickel (plate)	0.95	0.78	7440-02-0	7801
			Palladium (plate)	0.38	0.31	7440-05-3	3121
			Gold (plate)	0.06	0.05	7440-57-5	493
Chip	Silicon and inorganic compounds	6.20E-03			6.25		62477
			Silicon and trace metals	100.00	6.25	7440-21-3	62477
Die attach	Solder	2.40E-03			2.42		24185
			Tin	91.50	2.21	7440-31-5	22129
			Antimony	8.50	0.21	1309-64-4	2056
Solder Balls	Pb-free Solder	9.00E-03			9.07		90693
			Tin	95.20	8.63	7440-31-5	86340
			Silver	3.80	0.34	7440-22-4	3446
			Copper	1.00	0.09	7440-50-8	907
Terminal Finish	Pb-free Solder	1.43E-04			0.14		1441
			Nickel	95.60	0.14	7440-02-0	1378
			Palladium	3.80	0.01	7440-05-3	55
			Gold	0.60	0.00	7440-57-5	9

Materials Disclosure Disclaimer

The information provided in this Materials Disclosure is, to our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company. Also, there may not be information included in this statement regarding the minute amounts of dopant and metal materials contained within the electrically active or passive devices contained within the finished product.